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1. A. Name of conveying parties:	2	2. A. Name and address of receiving parties:	
1. Yoshitaka SASAKI 2. Hiroyuki ITO 3. Hiroshi IKEJIMA 4. Atsushi IIJIMA B. Additional name(s) of conveying	g party(ies) attached?  ☐ Yes ☑ No	1. HEADWAY TECHNOLOGIES, INC. 678 S. HILLVIEW DR., MILPITAS, CA 95035 U.S.A.  2. SAE MAGNETICS (H.K.) LTD. SAE TECHNOLOGY CENTRE,	
3. A. Nature of conveyance:  Assignment  Security Agreement  Other  B. Execution Date: 1 and 2- Ju 3 and 4- July 20, 2011	Merger Change of Name	SAE TECHNOLOGY CENTRE, 6 SCIENCE PARK EAST AVENUE HONG KONG SCIENCE PARK, SHATIN, N.T., HONG KONG, CHINA  B. Additional name(s) & address(es) attached?  □Yes ☑ No	
4. A. Patent Application No. 13/156	Additional numbers attached?		
		ND METHOD OF MANUFACTURING SAME	
Name and address of party to whom concerning document should be mailed     Name: <u>James A. Oliff</u> Address: <u>OLIFF &amp; BERRIDGE</u>	d: 7.		
P.O. Box 320850 Alexandria, V.A. 22320 Phone Number: 703-83 Fax Number: 703-836	0-4850 66-6400	Credit any overpayment or charge any underpayment to deposit account number 15-0461.	
9. Statement and signature.  To the best of my knowledge and believe original document.  James A. Oliff, Registration No. 27,07  Adam D. Brooke, Registration No. 58,	75	s true and correct and any attached copy is a true copy of the  Date: <u>August 4, 2011</u>	

PATENT REEL: 026724 FRAME: 0445

## ASSIGNMENT (Two Assignees)

	*						
		(1)	Yoshitaka SASAKI		(4)	Atsushi IIJIMA	
(1-8)	Insert Name(s) of Inventor(s)	(2)	Hiroyuki ITO		(5)		
		(3)	Hiroshi IKEJIMA				
		to each	In consideration of the su of the undersigned, each unde	m of one dollar (\$1.0	O) and	d other good and valuable consideration paid ad hereby does assign, transfer and set over to	
(9A)	Insert Name of First Assignee	(9A)	Headway Technologies				
(10A)	Insert Address of First Assignee	(10A)	678 S. Hillview Dr., M	ilpitas, CA 95035	5 U.S	S.A.	
(9B)	B) Insert Name of Second Assignee (9B) SAE Magnetics (H.K.) Ltd.					) de	
(10B)	Insert Address of Second Assignee	(10B)	SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T., Hong Kong, CHINA				
		§100. i	n the invention, and in all appr	and interest for the U	achid	line any and all provisional non-	
(11)	Insert Identification	provisi and all	n the invention, and in all app onal, divisional, continuation,	lications for patent i international, confir ssues and reexamina	mation o	ding any and all provisional, non- on, substitute and reissue application(s), certificates that may be granted on the IANUFACTURING SAME	
(11)	Insert Identification, such as Title, Case Number or Foreign Application Number	provisi and all inventi (11)	n the invention, and in all apponal, divisional, continuation, Letters Patent, extensions, rei on known as	dications for patent international, confires and reexamina	mation o	on, substitute and reissue application(s), certificates that may be granted on the	
(11)	Identification, such as Title, Case Number or Foreign	provisi and all inventi (11)  Attorne	n the invention, and in all apponal, divisional, continuation, Letters Patent, extensions, reion known as  LAYERED CHIP PACKAGE  by Docket No. 1498	dications for patent international, confir ssues and reexamina	matic tion o	on, substitute and reissue application(s), certificates that may be granted on the	
(11)	Identification, such as Title, Case Number or Foreign	provisi and all inventi (11)  Attorne	n the invention, and in all apponal, divisional, continuation, Letters Patent, extensions, reion known as  LAYERED CHIP PACKAGE  by Docket No. 1498  the undersigned has (have) of the herewith or	dications for patent international, confir ssues and reexamina	matic tion of OF M	on, substitute and reissue application(s), certificates that may be granted on the ANUFACTURING SAME	
	Identification, such as Title, Case Number or Foreign Application Number  Insert Date of Signing of	provisi and all inventi (11)  Attorne for whice	n the invention, and in all apponal, divisional, continuation, Letters Patent, extensions, reion known as  LAYERED CHIP PACKAGE  by Docket No. 1498  the undersigned has (have) of the herewith or	dications for patent international, confir ssues and reexaminates AND METHOD (1)	on for	on, substitute and reissue application(s), certificates that may be granted on the ANUFACTURING SAME	

- of, or any patent or reissue application based thereon, and to cooperate with the Assignees in every way possible in obtaining evidence and going forward with such interference.
- 3) Each undersigned agrees to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.
- 4) Each undersigned agrees to perform all affirmative acts which may be necessary to obtain, maintain or confirm by reissue or reexamination a grant of a valid United States patent to the Assignees.
- 5) Each undersigned authorizes and requests the Commissioner of the U.S. Patent and Trademark Office to issue any and all Letters Patents of the United States resulting from said application or any divisional, continuing or reissue applications to the said Assignees, as Assignees of the entire interest, and covenants that he has full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreements in conflict herewith, and agrees that this assignment is binding on him and his heirs, successors, assigns and legal representatives.
- 6) Each undersigned hereby grants the firm of OLIFF & BERRIDGE, PLC the power to insert on this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposit July 15, 2011 Date **Inventor Signature** (SEAL) July 15 2011 Date Inventor Signature (SEAL) July 20, 2011 Date **Inventor Signature** (SEAL) July 20, 2011 Date (SEAL) Date **Inventor Signature** (SEAL) Date **Inventor Signature** (SEAL) This assignment should preferably be signed before: (a) a Notary Public if within the U.S.A. (b) a U.S. Consul if outside the U.S.A. If neither, then it should be signed before at least two witnesses who also sign here: July 15, 2011 Date July 20, 2011 Date

**PATENT** 

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